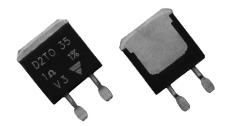




Surface Mount Power Resistor Thick Film Technology

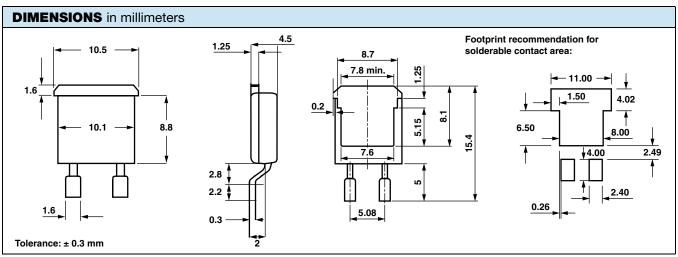


FEATURES

- AEC-Q200 qualified
- 35 W at 25 °C case temperature



- Surface mounted resistor TO-263 (D²PAK) style package
- Wide resistance range from 0.01 Ω to 550 $k\Omega$
- Non inductive
- · Resistor isolated from metal tab
- Solder reflow secure at 270 °C/10 s
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>



Notes

- For the asssembly on board, we recommend the lead (Pb)-free thermal profile as per J-STD-020C
- Power dissipation is 3.3 W at an ambient temperature of 25 °C when mounted on a double sided copper board using FR4 standard, 70 μm of copper, 39 mm x 30 mm x 1.6 mm

STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER P _{25 °C} W	LIMITING ELEMENT VOLTAGE <i>U</i> L V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C	$\begin{array}{c} \text{CRITICAL} \\ \text{RESISTANCE} \\ \Omega \end{array}$
D2TO35	TO-263	0.01 to 550K	35	500	1, 2, 5, 10	150, 250, 700, 1100	7.14K

MECHANICAL SPECIFICATIONS			
Mechanical Protection Molded			
Resistive Element	Thick film		
Substrate	Alumina		
Connections	Tinned copper		
Weight	2.2 g max.		

ENVIRONMENTAL SPECIFICATIONS				
Temperature Range	- 55 °C to 175 °C			
	IEC 60695-11-5			
Flammability	2 applications 30 s separated by 60 s			

TECHNICAL SPECIFICATIONS				
Power Rating and Thermal Resistance of the Component	35 W at 25 °C (case temperature) R _{TH (j - c)} : 4.28 °C/W			
Temperature Coefficient	See Special Feature table			
Standard	± 150 ppm/°C			
Dielectric Strength IEC 60115-1	2000 V _{RMS} - 1 min - 10 mA max. (between terminals and board)			
Insulation Resistance	$\geq 10^6 \ M\Omega$			
Inductance	≤ 0.1 µH			

DIMENSIONS	
Standard Package	TO-263 style (D ² PAK)



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SPECIAL FEATURES					
Resistance Values	≥ 0.010	≥ 0.045	≥ 0.1	≥ 0.5	
Tolerances	± 1 % at ± 10 %				
Requirement Temperature Coefficient (TCR) (- 55 °C + 150 °C) IEC 60115-1	± 1100 ppm/°C	± 700 ppm/°C	± 250 ppm/°C	± 150 ppm/°C	

PERFORMANCE				
TESTS	CONDITIONS	REQUIREMENTS		
Momentary Overload	IEC 60115-1 §4.13 1.7 Pr 5 s for $R < 2$ Ω 1.4 Pr 5 s for $R \ge 2$ Ω US < 1.5 UL	± (0.25 % + 0.005 Ω)		
Load Life	IEC 60115-1 1000 h, 90/30 Pr at + 25 °C	± (1 % + 0.005 Ω)		
High Temperature Exposure	AEC-Q200 REV C conditions: MIL-STD-202 method 108 1000 h, + 175 °C, unpowered	$\pm (0.25 \% + 0.005 \Omega)$		
Temperature Cycling	Pre-conditioning 3 reflows according JESTD020D IEC 60068-2-14 test Na 1000 cycles, - 55 °C, + 175 °C Dwell time - 15 min	\pm (0.5 % + 0.005 Ω)		
Moisture Resistance	AEC-Q200 REV C conditions: MIL-STD-202 method 106 10 cycles, 24 h, unpowered	± (0.5 % + 0.005 Ω)		
Biased Humidity	AEC-Q200 REV C conditions: MIL-STD-202 method 103 1000 h, 85 °C, 85% RH	\pm (1 % + 0.005 Ω)		
Operational Life	AEC-Q200 REV C conditions: Pre-conditioning 3 reflows according JESTD020D MIL-STD-202 method 108 1000 h, 90/30, powered, + 125 °C	± (1 % + 0.005 Ω)		
ESD Human Body Model	AEC-Q200 REV C conditions: AEC-Q200-002 25 kV _{AD}	± (0.5 % + 0.005 Ω)		
Vibration	AEC-Q200 REV C conditions: MIL-STD-202 method 204 5 g's for 20 min, 12 cycles test from 10 Hz to 2000 Hz	± (0.5 % + 0.005 Ω)		
Mechanical Shock	AEC-Q200 REV C conditions: MIL-STD-202 method 213 100 g's, 6 ms, 3.75 m/s 3 shocks/direction	± (0.5 % + 0.005 Ω)		
Board Flex	AEC-Q200 REV C conditions: AEC-Q200-005 bending 2 mm, 60 s	± (0.25 % + 0.01 Ω)		
Terminal Strength	AEC-Q200 REV C conditions: AEC-Q200-006 1.8 kgf, 60 s	± (0.25 % + 0.01 Ω)		

ASSEMBLY SPECIFICATIONS					
For the assembly on board, we recommend the lead (Pb)-free thermal profile as per J-STD-020C					
TESTS	CONDITIONS	REQUIREMENTS			
Resistance to Soldering Heat	IEC 60115-1 IEC 60068-2-58 Solder bath method: 270 °C/10 s	± (0.5 % + 0.005 Ω)			
Moisture Sensitivity Level (MSL)	IPC/JEDEC J-STD-020C 85 °C/85 % RH/168 h	Level: 1 + pass requirements of TCR overload and dielectic strength after MSL			



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CHOICE OF THE BOARD

The user must choose the board according to the working conditions of the component (power, room temperature). Maximum working temperature must not exceed 175 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{R_{TH (j-c)} + R_{TH (c-h)} + R_{TH (h-a)}}$$
(1)

P: Expressed in W

ΔT: Difference between maximum working temperature and room temperature or fluid cooling temperature

R_{TH (j - c)}: Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal resistance of the component: 4.28 °C/W.

R_{TH (c - h)}: Thermal resistance value measure 4.28 °C/W. Outer side of the resistor and upper side of the board. This is the thermal resistance of the solder layer.

R_{TH (h - a)}: Thermal resistance of the board.

Example:

R_{TH (c - h)} + R_{TH (h - a)} for D2TO35 power rating 3.5 W at ambient temperature + 25 °C.

Thermal resistance R_{TH (j - c)}: 4.28 °C/W

Considering equation (1) we have:

$$R_{TH (j-c)} + R_{TH (c-h)} + R_{TH (h-a)} = \Delta T/P = 150/3.5 = 42.8 \text{ °C/W}$$

$$R_{TH (c-h)} + R_{TH (h-a)} = 42.8 \text{ °C/W} - 4.28 \text{ °C/W} = 38.52 \text{ °C/W}$$

Single Pulse:

These informations are for a single pulse on a cold resistor at 25 °C (not already used for a dissipation) and for pulses of 100 ms maximum duration.

The formula used to calculate *E* is:

$$E = P \times t = \frac{U^2}{R} \times t$$

with:

E (J): Pulse energy

P (W): Pulse power

t (s): Pulse duration

U (V): Pulse voltage

R (W): Resistor

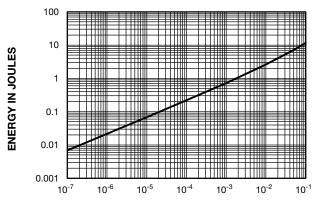
The energy calculated must be less: than that allowed by the graph.



OVERLOADS

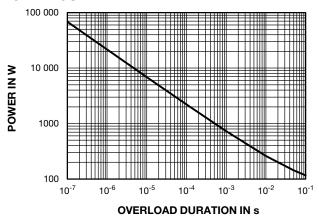
In any case the applied voltage must be lower than the maximum overload voltage of 750 V. The values indicated on the graph below are applicable to resistors in air or mounted onto a board.

ENERGY CURVE



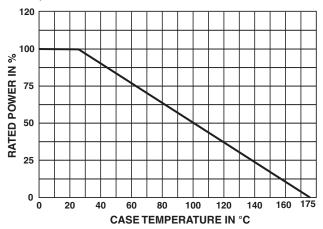
OVERLOAD DURATION IN s

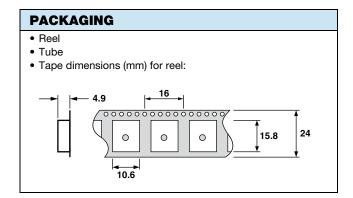
POWER CURVE



POWER RATING

The temperature of the case should be maintained within the limits specified.





MARKING

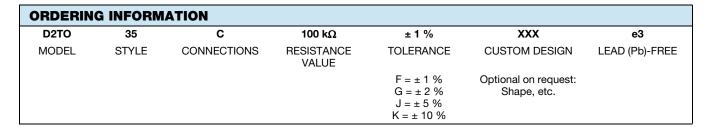
Model, style, resistance value (in Ω), tolerance (in %), manufacturing date, Vishay Sfernice trademark

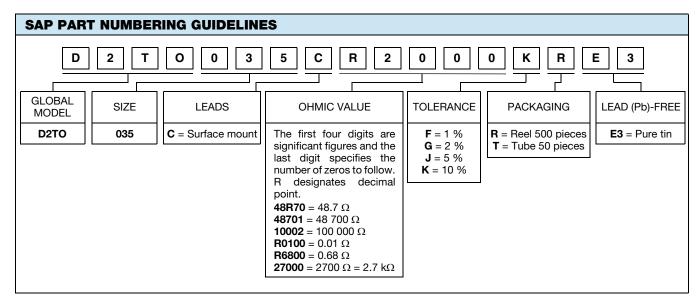




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